

TOSHIBA Bipolar Linear Integrated Circuit Silicon Monolithic

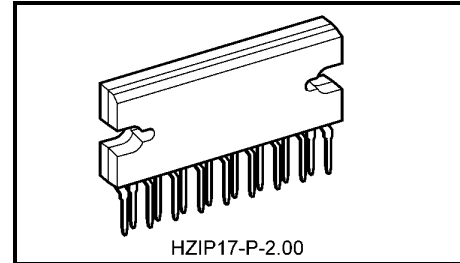
TA8233BHQ

30W BTL × 2ch Audio Power Amplifier

The thermal resistance θ_{j-T} of TA8233BHQ package designed for low thermal resistance, has high efficiency of heat radiation.

The temperature rise of chip can be reduced, and the influence from the degradation of the features due to the temperature rise at the high output can also be reduced.

This stereo audio power IC, designed for car audio use, has two built-in channels to reduce the characteristic difference between L and R channels. It also contains output short detection circuit, output clip detection and various kind of protection.



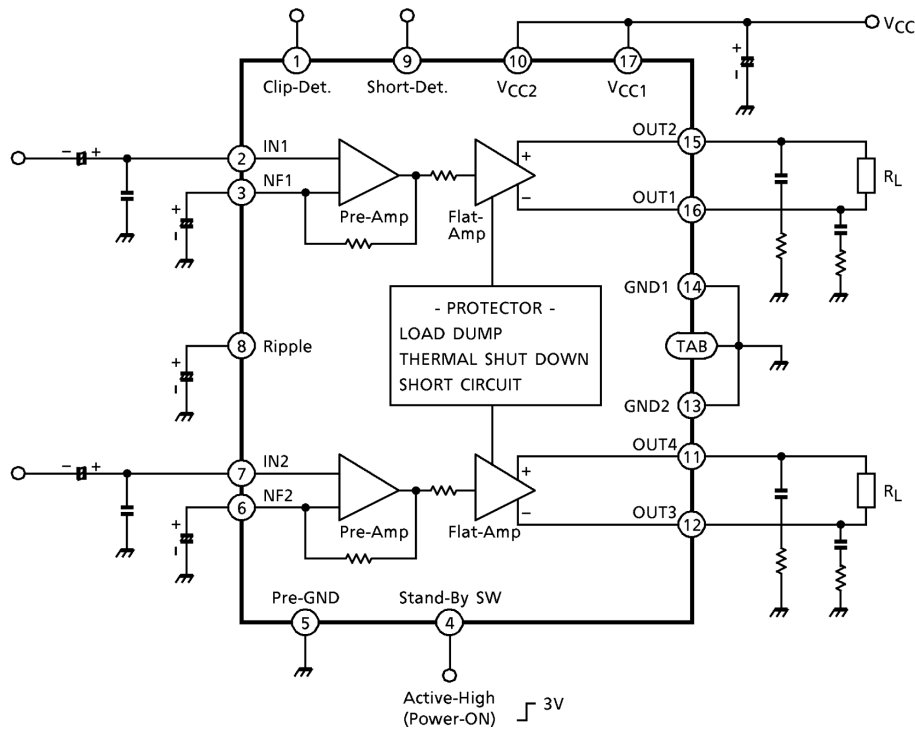
Weight: 9.8g (typ.)

Features

- High power
 - : $POUT(1) = 30W$ (typ.) / channel
($VCC = 14.4V$, $f = 1kHz$, $THD = 10\%$, $R_L = 2\Omega$)
 - $POUT(2) = 26W$ (typ.) / channel
($VCC = 13.2V$, $f = 1kHz$, $THD = 10\%$, $R_L = 2\Omega$)
 - $POUT(3) = 19W$ (typ.) / channel
($VCC = 13.2V$, $f = 1kHz$, $THD = 10\%$, $R_L = 4\Omega$)
- Low thermal resistance: $\theta_{j-T} = 1.5^\circ C / W$ (infinite heat sink)
- Low distortion ratio: $THD = 0.04\%$ (typ.)
($VCC = 13.2V$, $f = 1kHz$, $POUT = 1W$, $R_L = 4\Omega$, $G_V = 50dB$)
- Low noise: $V_{NO} = 0.30mV_{rms}$ (typ.)
($VCC = 13.2V$, $R_L = 4\Omega$, $G_V = 50dB$, $R_g = 0\Omega$, $BW = 20Hz \sim 20kHz$)
- Built-in stand-by function
 - : (with pin(4) set at low, power is turned off.) $ISB = 1\mu A$ (typ.)
- Built-in output clip detection circuit
 - : (pin(1): Open collector (active low))
- Built-in output short detection circuit
 - : (pin(9): Open collector (active low))
- Built-in various protection circuits
 - : Thermal shut down, Over voltage, Out \rightarrow VCC short, Out \rightarrow GND short and Out- \rightarrow Out short.
- Operating supply voltage: $VCC(opr) = 9 \sim 18V$

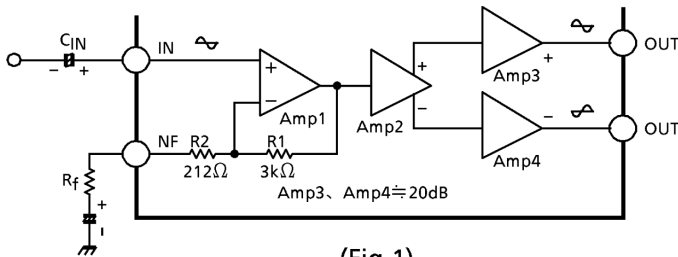
Block Diagram

TA8233BHQ ($G_V = 50\text{dB}$)



Caution And Application Method
(description is made only on the single channel.)

1. Voltage gain adjustment



- Amp1 : Pre-Amp
- Amp2 : Phase Amp
- Amp3 : POWER Amp (Flat-Amp)
- Amp4 : POWER Amp (Flat-Amp)

(Fig.1)

This IC has the amplifier constructions as shown in Fig.1. The pre-amp (amp 1) is provided to the primary stage, and the input voltage is amplified by the flat amps, amp 3 and amp 4 of each channel through the phase amp (amp 2).

Since the input offset is prevented by pre-amp when VCC is set to on, this circuit can remarkably reduce the pop noise.

The total closed loop gain G_V of this IC can be obtained by expression below when the closed loop voltage gain of amp 1 is G_{V1} .

$$G_{V1} = 20 \log \frac{R1 + (R_f + R2)}{R_f + R2} \text{ (dB)} \dots\dots\dots (1)$$

The closed loop voltage gain of power amp, amp 3 and amp 4 is fixed at $G_{V3} \cong G_{V4} = 20\text{dB}$. Therefore, the total closed circuit voltage gain G_V is obtained through BTL connection by the expression as below.

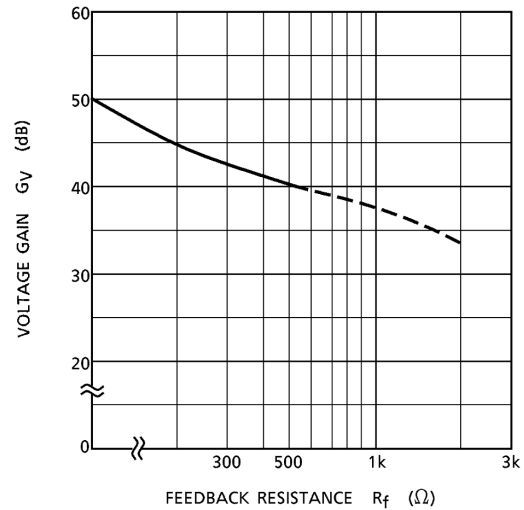
$$G_V = G_{V1} + G_{V3} + 6 \text{ (dB)} \dots\dots\dots (2)$$

For example, when $R_f = 0\Omega$, G_V is obtained by the expressions (1) and (2) as below.

$$G_V \cong 24 + 20 + 6 = 50\text{dB}$$

The voltage gain is reduced when R_f is increased. (Fig.2)

With the voltage gain reduced, since (1) the oscillation stability is reduced, and (2) the pop noise changes when V_{CC} is set to on, refer to the items 3 and 4.



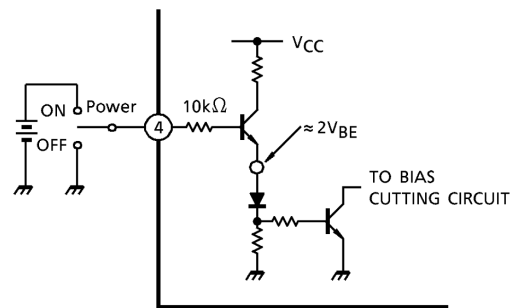
(Fig.2)

2. Stand-by SW function

By means of controlling pin(4) (stand-by terminal) to high and low, the power supply can be set to on and off. The threshold voltage of pin(4) is set at 2.1V ($3V_{BE}$), and the power supply current is about 1 μ A (typ.) at the stand-by state.

Control voltage of pin(4): $V(SB)$

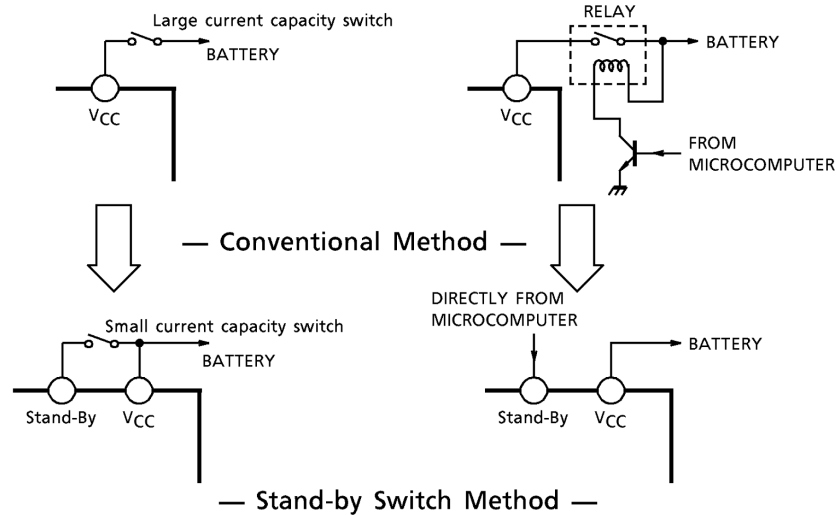
Stand-By	Power	$V(SB)$ (V)
On	Off	0~2
Off	On	$3 \sim V_{CC}$



(Fig.3) With pin④ set to High, Power is turned ON

Adjustage of stand-by SW

- (1) Since V_{CC} can directly be controlled to on or off by the microcomputer, the switching relay can be omitted.
- (2) Since the control current is microscopic, the switching relay of small current capacity is satisfactory for switching



3. Preventive measure against oscillation

For preventing the oscillation, it is advisable to use C4, the condenser of polyester film having small characteristic fluctuation of the temperature and the frequency. The condenser (C6) between input and GND is effective for preventing oscillation which is generated with a feedback signal from a output stage. The resistance R to be series applied to C4 is effective for phase correction of high frequency, and improves the oscillation allowance.

- (1) Voltage gain to be used (GV setting)
- (2) Capacity value of condenser
- (3) Kind of condenser
- (4) Layout of printed board

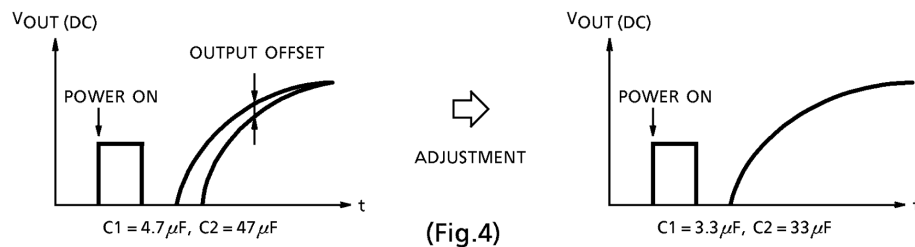
In case of its use with the voltage gain GV reduced or with the feedback amount increased, care must be taken because the phase-inversion is caused by the high frequency resulting in making the oscillation liable generated.

4. Adjustment of output offset (when the power supply turn on)

As this IC is constructed with DC circuit on the pre-amp stage, it is necessary to lower a input offset or output offset by agreement with the each leading edge time constant of the input voltage in the pre-amp stage and NF terminal voltage.

Concretely, monitor the output DC voltage and vary the capacity value in input condenser and NF condenser (see Fig.4)

(Reference) In case of setting the condition (GV = 40dB) with $R_f = 470\Omega$



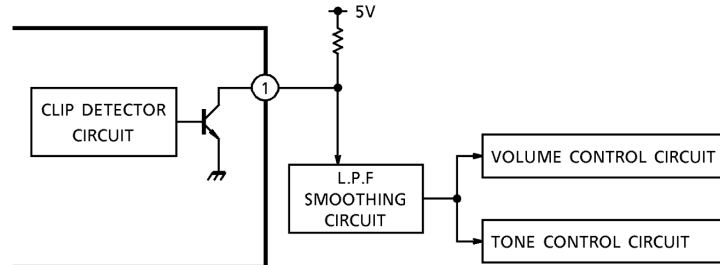
5. Output clip detection function (pin(1))

The output clip detection terminal of pin(1) has the open collector output structure on chip as shown in Fig.5. In case that the output waveform is clipping, the clip detection circuit is operated and NPN Tr. is turned on.

It is possible to improve the tone quality with the current of flowing into pin(1) and with controlling the volume, tone control circuit through L.P.F smoothing circuit as shown in Fig.5.

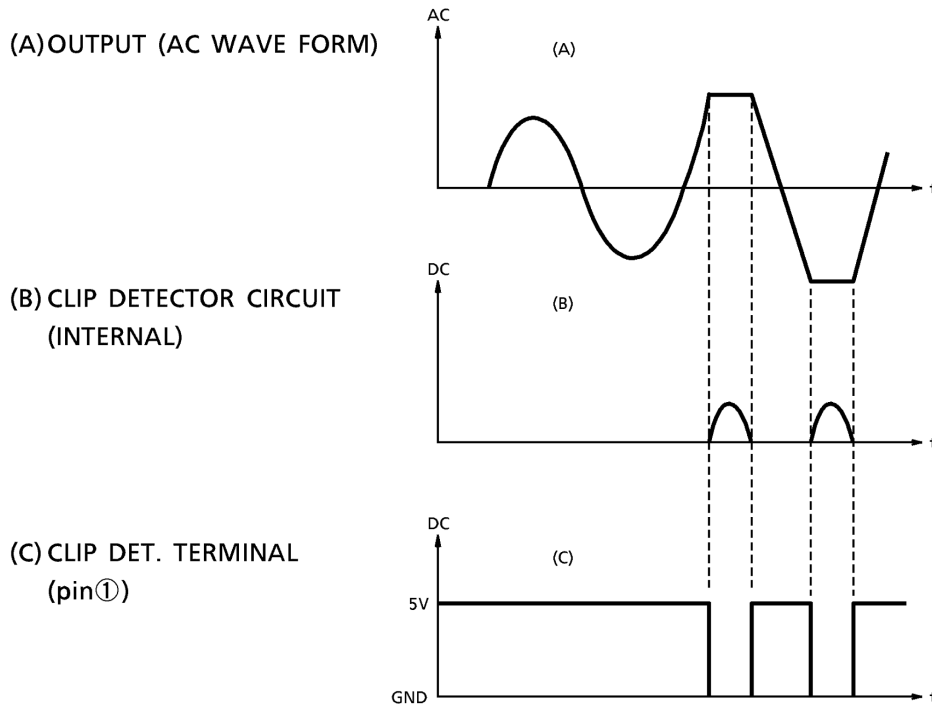
In case of being unused this function, use this IC as open connection on pin(1).

(Application)



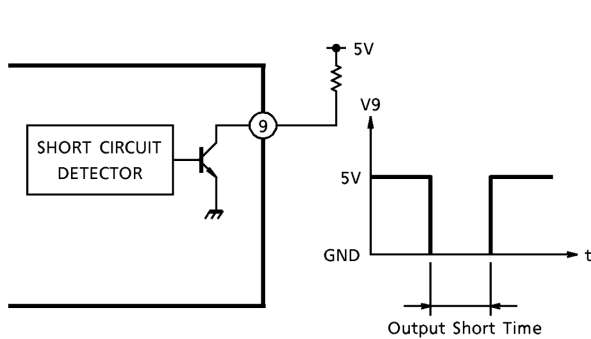
pin① : Open Collector Output (Active Low)

(Fig.5)



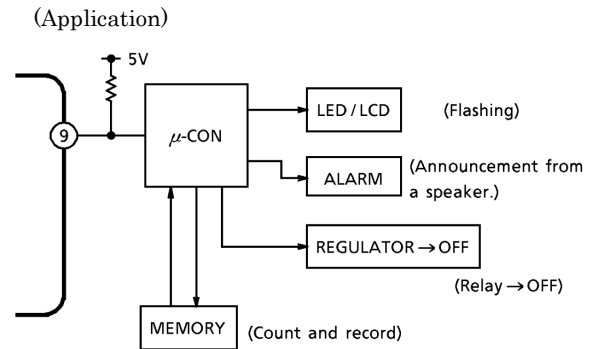
6. Output to VCC, output to gnd short detection function (pin(9))

The output short detection terminal of pin(9) has open collector output structure on chip as shown in Fig.6. In unusual case that output terminal of power amp. Is condition of output to VCC or output to GND short, it is possible to protect all the system of apparatus as well as power IC protection. In case of being unused this function, use this IC as open-connection on pin(9).



pin⑨ : Open Collector Output (Active Low)

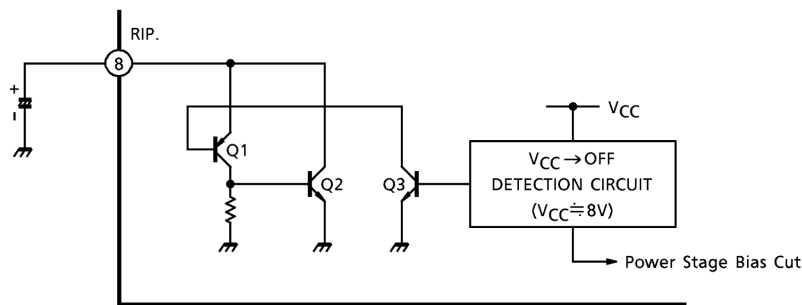
(Fig.6)



(Fig.7)

7. Rapid ripple discharging circuit at the time of VCC off

This circuit is effective in such a mode where the VCC and the stand-by terminals become high or low simultaneously; for instance, for a pop noise produced when the power is turned on or off repeatedly by operating the ignition key.



(Fig.8)

When VCC is off, this detection circuit detect $V_{CC} \approx 8V$ internally on IC.

- (1) The power stage bias circuit is cut.
- (2) pin(8): Ripple capacitor is rapidly discharged by turning Q3 on and then Q1 and Q2 on.

(Precaution 1)

When the stand-by terminal was put to the low level after the ripple rapid discharging circuit was operated ($V_{CC} \approx 8V$) at the time when V_{CC} was turned off, a pop noise may be generated. Therefore, V_{CC} which makes the stand-by terminal low shall be set at 8V or above so that (1) the stand-by terminal is put at the low level and (2) the ripple rapid discharging circuit is turned off when V_{CC} is turned off (in order of (1) and (2)). An example of application is shown in Fig.9.

(Precaution 2)

If the falling time constant of the V_{CC} line is large (the fall is gentle), the pop noise may become worse. In this case, it is possible to prevent the pop noise from becoming worse by reducing the ability of “ripple rapid discharging circuit at the time of V_{CC} off” according to the increase of the capacity of ripple capacitor of pin(8). However, it shall be kept in mind that the time for turning the power on becomes longer as the result of this method.

8. External part list and description

Sym- bol	Recommended Value	Feature	Influence		Remarks
			Smaller Than Recommended Value	Larger Than Recommended Value	
C1	4.7 μ F	DC blocking	Related to pop noise at $V_{CC} \rightarrow on$.		Related to gain. Refer to item 4.
C2	47 μ F	Feedback condenser	Related to pop noise at $V_{CC} \rightarrow on$.		
			Determination of low cut-off frequency $C2 = \frac{1}{2\pi \cdot f_L \cdot R_f}$		
C3	220 μ F	Ripple reduction	Time constant is small at $V_{CC} \rightarrow on$ or off.	Time constant is large at $V_{CC} \rightarrow on$ or off.	
C4	0.12 μ F	Oscillation prevention	Made liable to oscillate.	Oscillation allowance	Refer to item 3.
C5	1000 μ F	Ripple filter	For filtering power supply hum and ripple. Large at using AC rectified power supply. Small at using DC power supply.		
C6	1000pF	Oscillation prevention	Oscillation allowance improved. Noise reduction		Refer to item 3.

Absolute Maximum Ratings (Ta = 25°C)

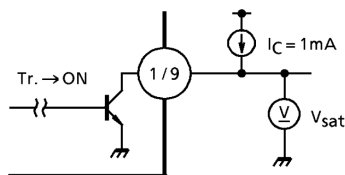
Characteristic	Symbol	Rating	Unit
Peak supply voltage (0.2s)	V _{CC} (surge)	50	V
DC supply voltage	V _{CC} (DC)	25	V
Operating supply voltage	V _{CC} (opr)	18	V
Output current (peak)	I _O (peak)	9	A
Power dissipation	P _D	50	W
Operating temperature	T _{opr}	-30~85	°C
Storage temperature	T _{stg}	-55~150	°C

Electrical Characteristics

(unless otherwise specified, V_{CC} = 13.2V, R_L = 4Ω, f = 1kHz, Ta = 25°C)

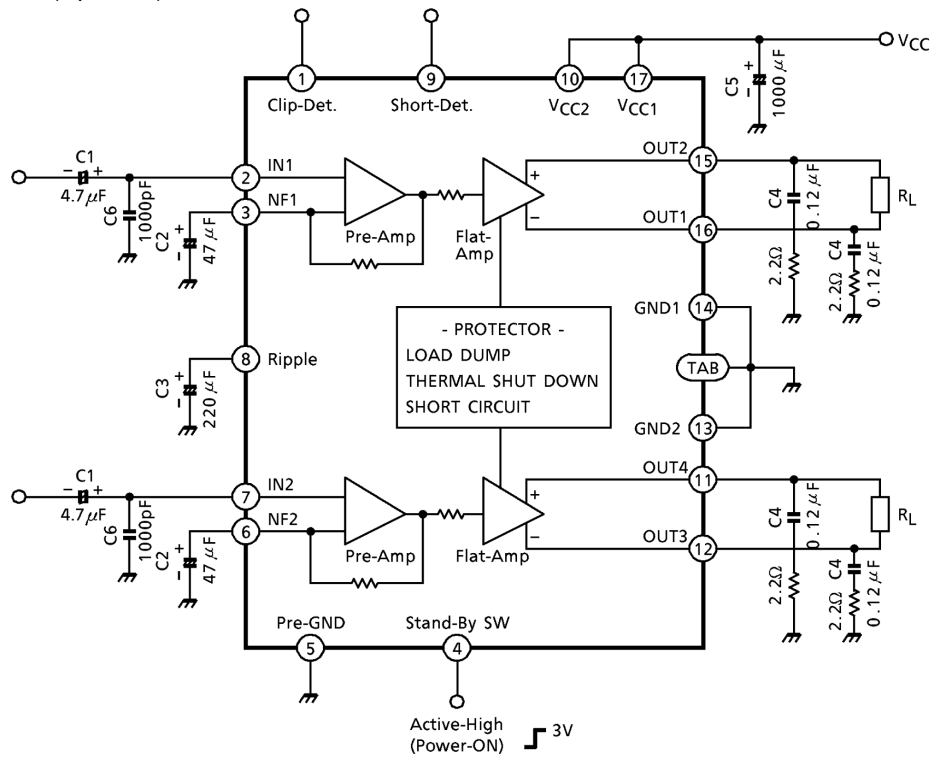
Characteristic	Symbol	Test Circuit	Test Condition	Min.	Typ.	Max.	Unit
Quiescent supply current	I _{CCQ}	—	V _{IN} = 0	—	120	250	mA
Output power	P _{OUT} (1)	—	V _{CC} = 14.4V, R _L = 2Ω THD = 10%	—	30	—	W
	P _{OUT} (2)	—	R _L = 2Ω, THD = 10%	17	26	—	
	P _{OUT} (3)	—	THD = 10%	16	19	—	
Total harmonic distortion ratio	THD	—	P _{OUT} = 1W	—	0.04	0.4	%
Voltage gain	G _V	—	—	48	50	52	dB
Voltage gain ratio	ΔG _V	—	—	-1.0	0	1.0	dB
Output noise voltage	V _{NO}	—	R _g = 0Ω, BW = 20Hz~20kHz	—	0.3	0.7	mV _{rms}
Ripple rejection ratio	R.R.	—	f _{ripple} = 100Hz, R _g = 600Ω	40	54	—	dB
Input resistance	R _{IN}	—	—	—	30	—	kΩ
Output offset voltage	V _{offset}	—	V _{IN} = 0	-100	0	100	mV
Current at stand-by state	I _{SB}	—	—	—	1	10	μA
Cross talk	C.T.	—	R _g = 600Ω V _{OUT} = 0.775V _{rms} (0dBm)	—	60	—	dB
Pin(4) control voltage	V _{SB}	—	Stand-by→off (power→on)	2.5	—	V _{CC}	V
Pin(1) (clip DET) saturation voltage	V _{sat} (1)	—	I _C = 1mA	—	100	—	mV
Pin(9) (short DET) saturation voltage	V _{sat} (9)	—	I _C = 1mA	—	100	—	mV

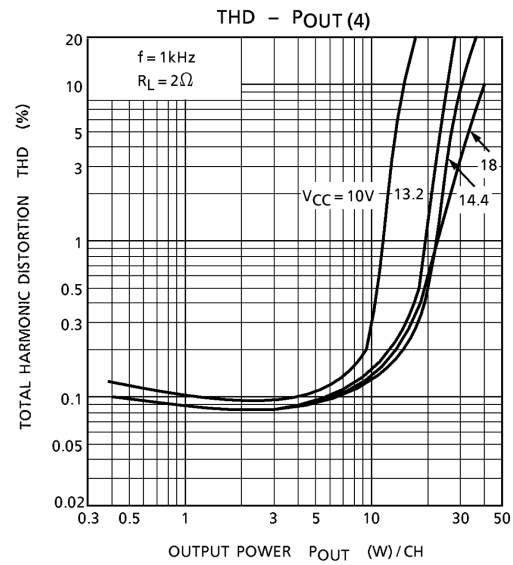
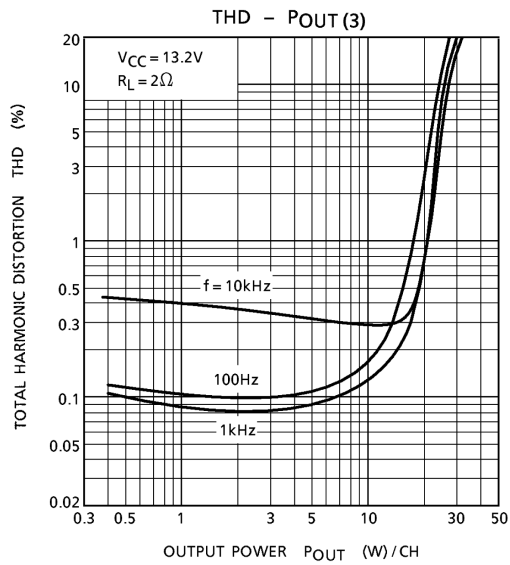
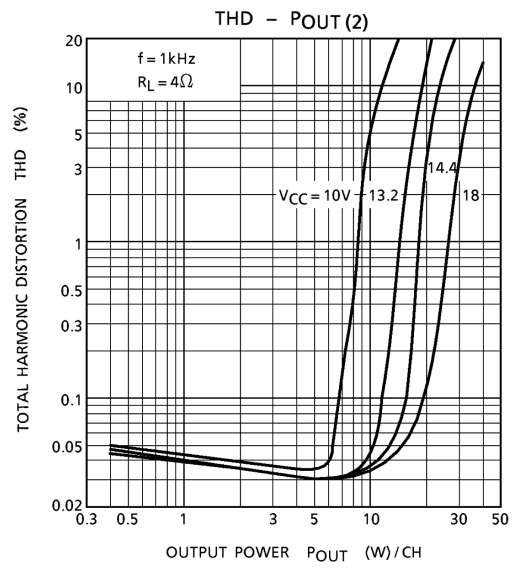
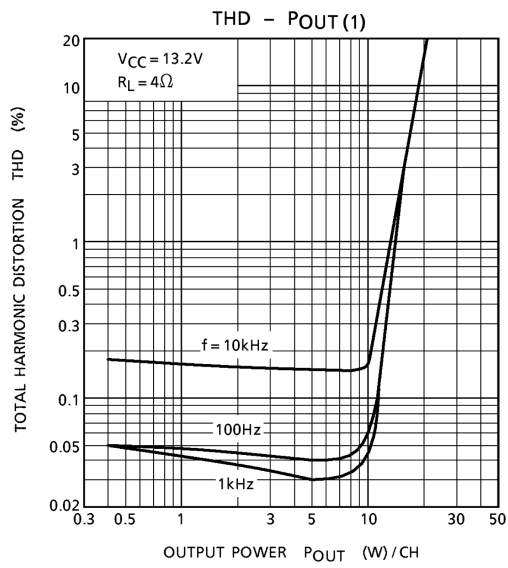
V_{sat} (1), V_{sat} (9) Test Circuit

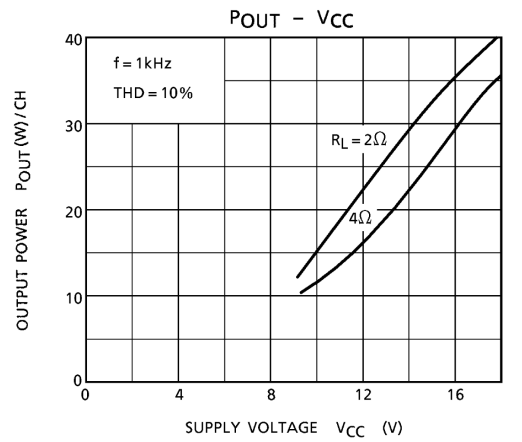
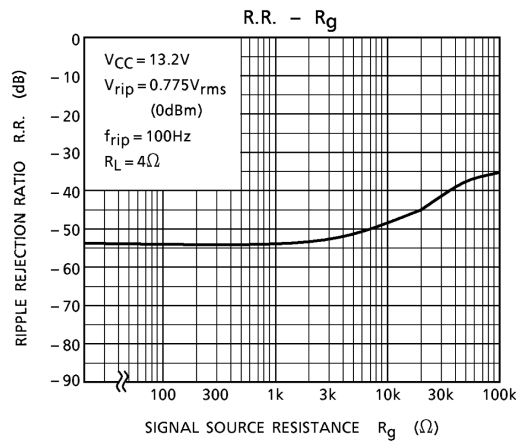
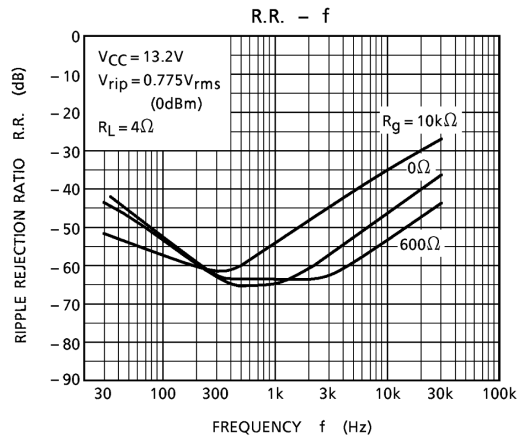
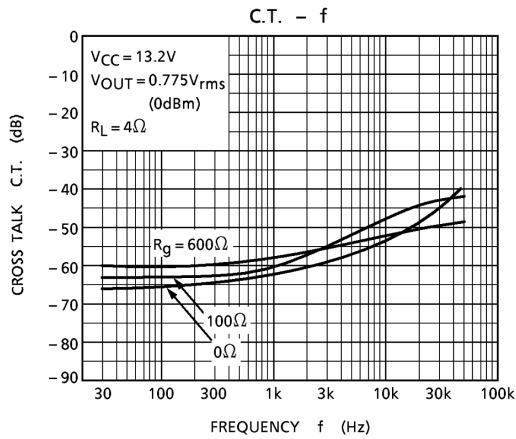
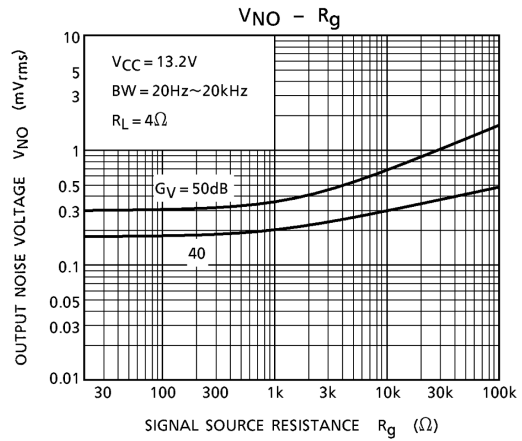
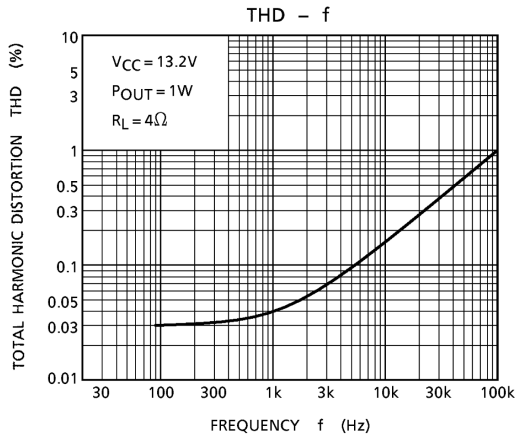


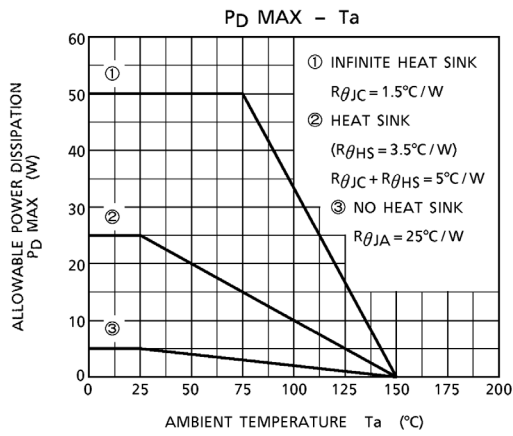
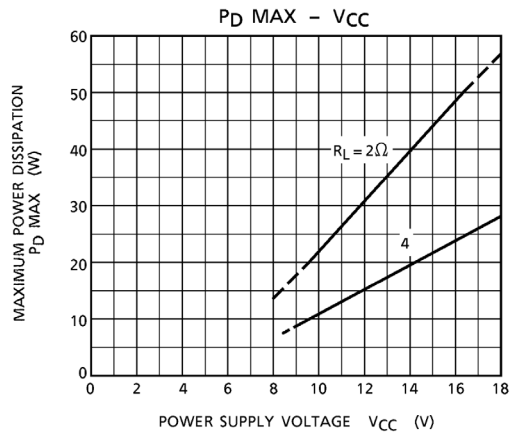
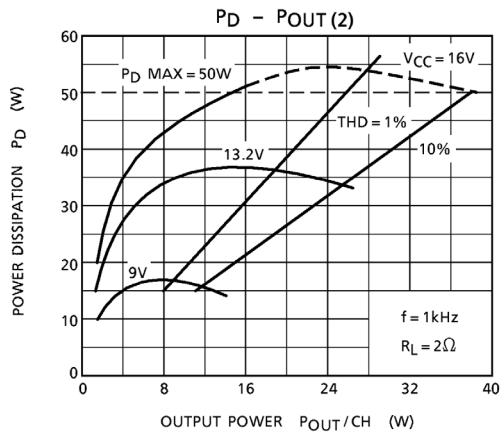
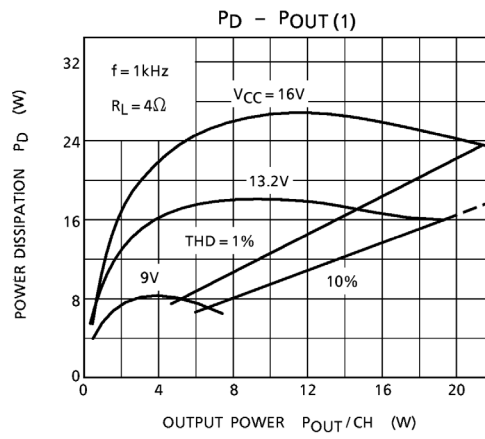
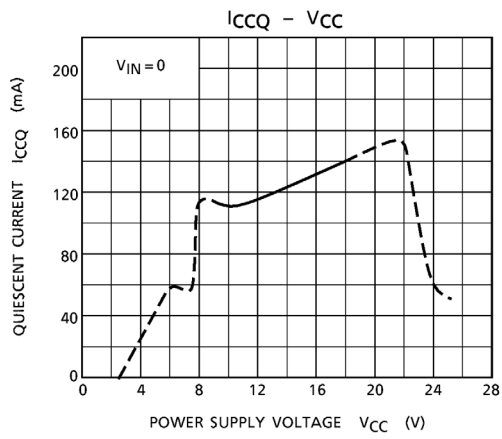
Test Circuit

TA8233BHQ (G_v = 50dB)





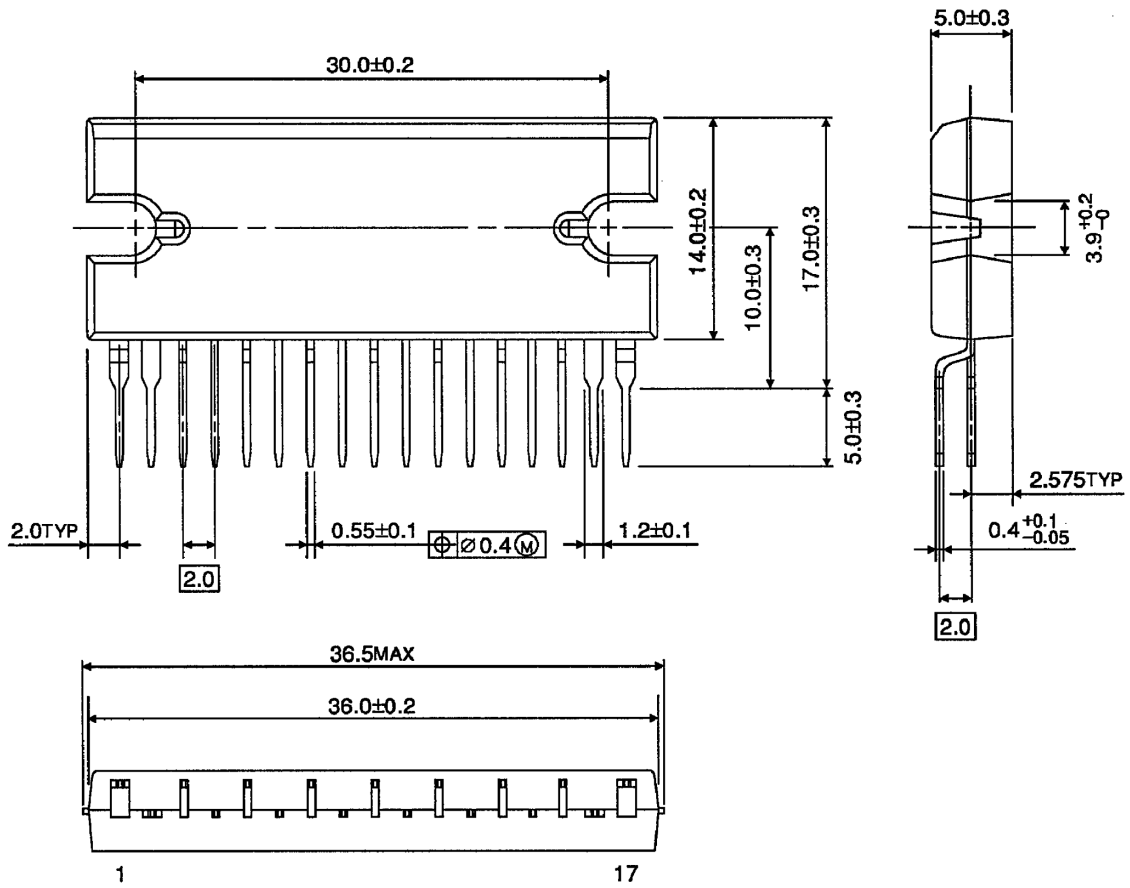




Package Dimensions

HZIP17-P-2.00

Unit : mm



Weight: 9.8g (typ.)

- Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. For details on how to connect a protection circuit such as a current limiting resistor or back electromotive force adsorption diode, refer to individual IC datasheets or the IC databook. IC breakdown may cause injury, smoke or ignition.
- Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator. If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.
- Over current Protection Circuit
Over current protection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the Over current protection circuits operate against the over current, clear the over current status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current protection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.
- Thermal Shutdown Circuit
Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the Thermal shutdown circuits operate against the over temperature, clear the heat generation status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the thermal shutdown circuit to not operate properly or IC breakdown before operation.
- Heat Radiation Design
When using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (T_j) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.
- Installation to Heat Sink
Please install the power IC to the heat sink not to apply excessive mechanical stress to the IC. Excessive mechanical stress can lead to package cracks, resulting in a reduction in reliability or breakdown of internal IC chip. In addition, depending on the IC, the use of silicon rubber may be prohibited. Check whether the use of silicon rubber is prohibited for the IC you intend to use, or not. For details of power IC heat radiation design and heat sink installation, refer to individual technical datasheets or IC databooks.

RESTRICTIONS ON PRODUCT USE

060116EBF

- The information contained herein is subject to change without notice. 021023_D
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- The products described in this document are subject to the foreign exchange and foreign trade laws. 021023_E
- This product generates heat during normal operation. However, substandard performance or malfunction may cause the product and its peripherals to reach abnormally high temperatures.
The product is often the final stage (the external output stage) of a circuit. Substandard performance or malfunction of the destination device to which the circuit supplies output may cause damage to the circuit or to the product. 030619_R

About solderability, following conditions were confirmed

- Solderability
 - (1) Use of Sn-37Pb solder Bath
 - solder bath temperature = 230°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux
 - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
 - solder bath temperature = 245°C
 - dipping time = 5 seconds
 - the number of times = once
 - use of R-type flux